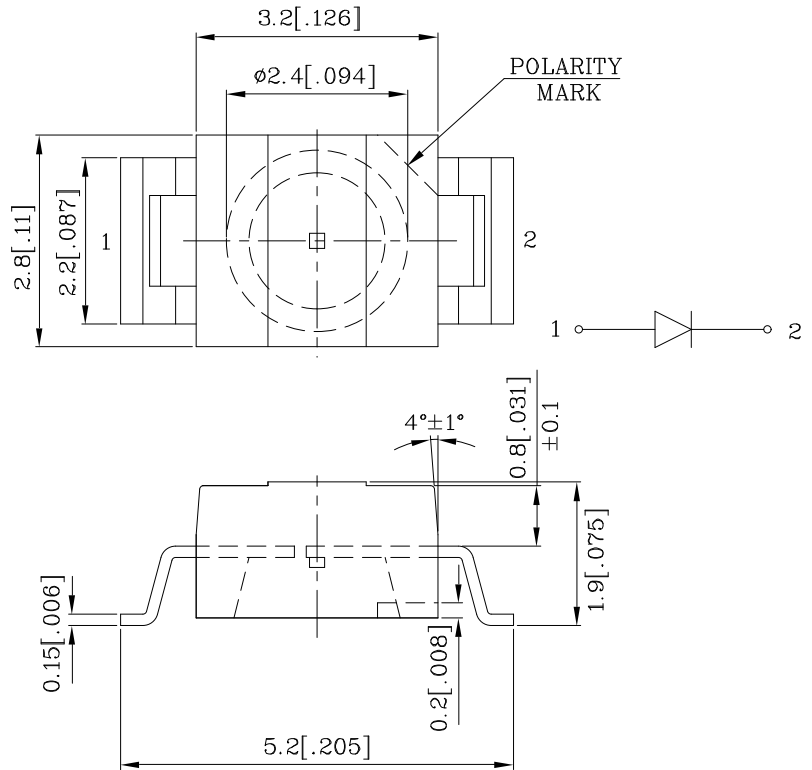


Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- PACKAGE : 1500PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



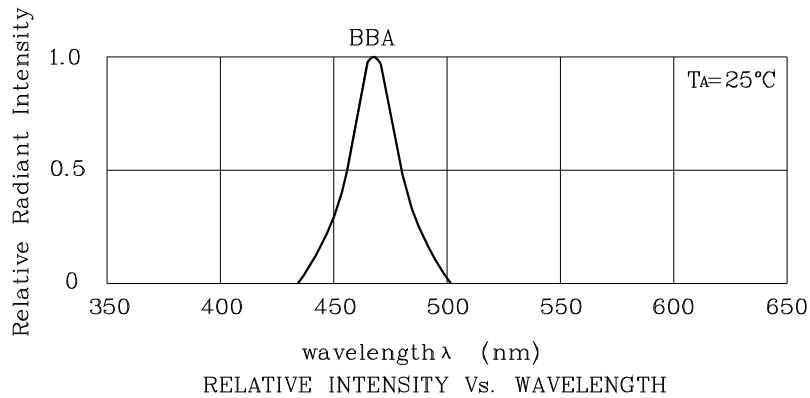
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ " unless otherwise noted.
3. Specifications are subject to change without notice.

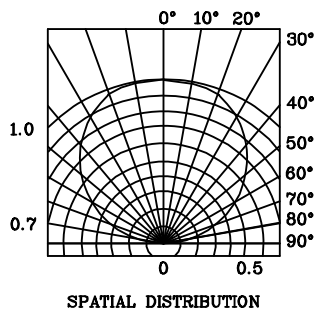
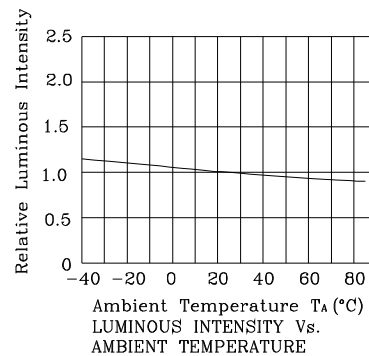
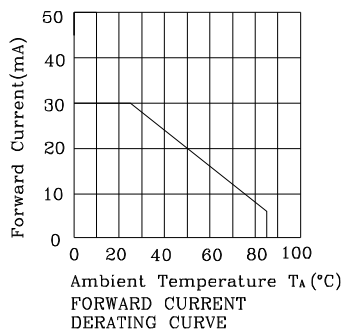
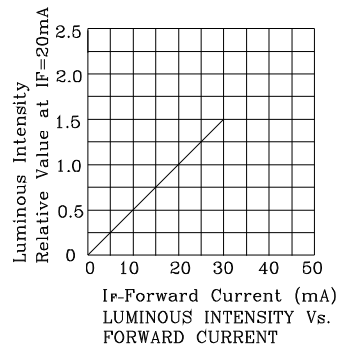
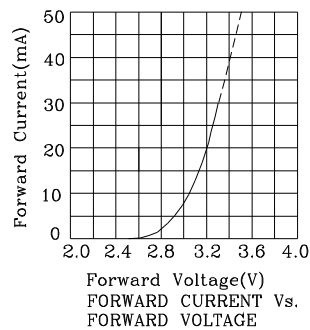
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		BBA (InGaN)	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	100	mA
Power Dissipation	P_T	120	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V

Operating Characteristics ($T_A=25^\circ\text{C}$)		BBA (InGaN)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	3.2	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	4.0	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	μA
Wavelength Of Peak Emission (Typ.) ($I_F=20\text{mA}$)	λ_P	468	nm
Wavelength Of Dominant Emission (Typ.) ($I_F=20\text{mA}$)	λ_D	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	21	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	100	pF

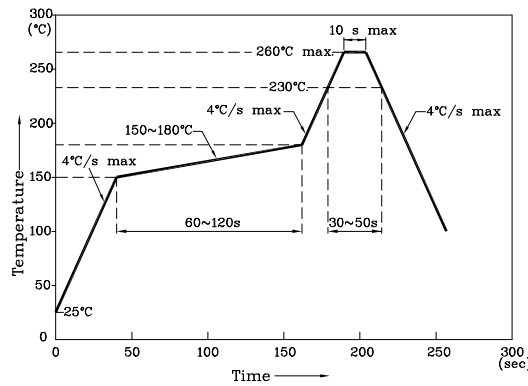
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=20\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle 2θ 1/2
				min.	typ.		
XZBBA45FW-9	Blue	InGaN	Water Clear	18	59	468	120°
Published Date : JAN 23, 2008 Drawing No : XDSB1722 V1 Checked : B.LLIU P. 1/4							



❖ BBA

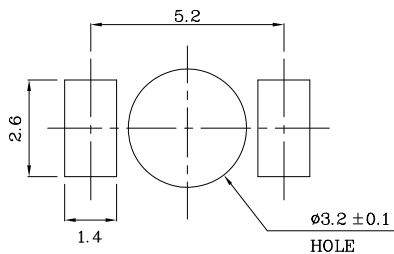


Reflow Soldering Profile For Lead-free SMT Process.

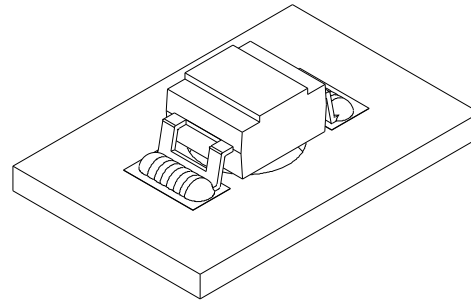


- NOTES:
1. Maximum soldering temperature should not exceed 260°C.
 2. Recommended reflow temperature: 145°C-260°C.
 3. Do not put stress to the epoxy resin during high temperatures conditions.

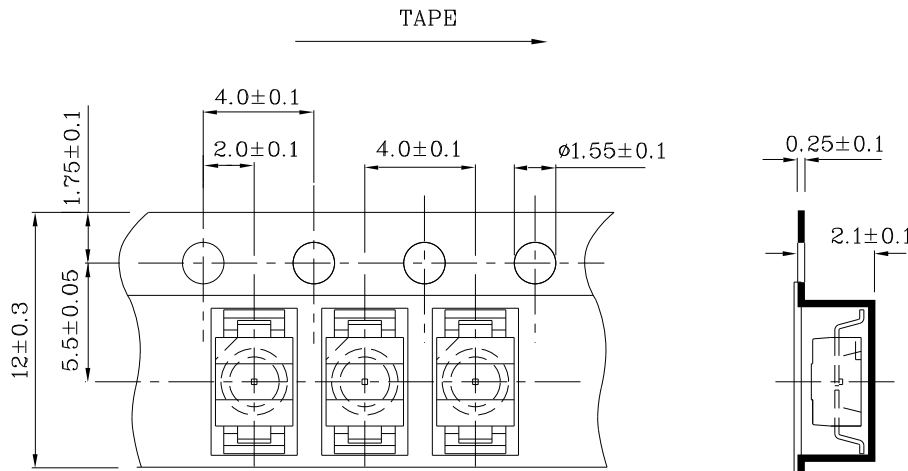
❖ **Recommended Soldering Pattern**
(Units : mm; Tolerance: ±0.1)



❖ **The device has a single mounting surface. The device must be mounted according to the specifications.**



❖ **Tape Specification (Units : mm)**



Remarks:

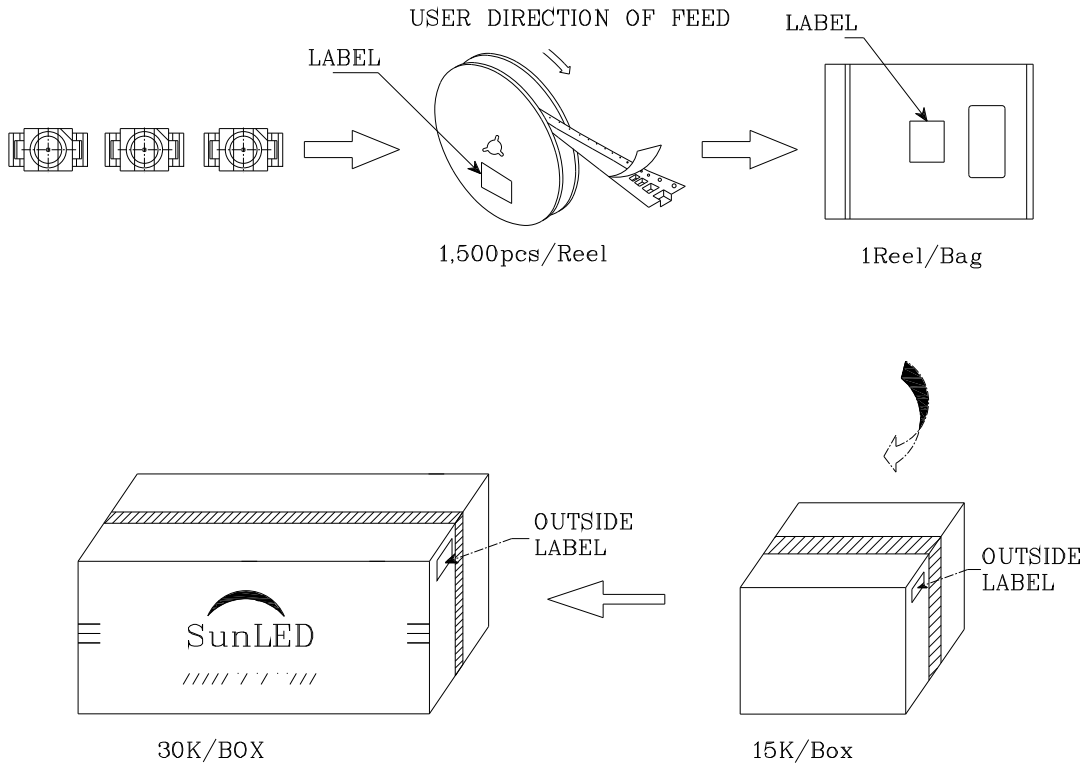

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

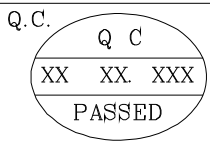

1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XZBBA45FW-9

	
P/NO : XZxx45x9	
QTY : 1,500 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	